

**Amendment to the Specification**

Please replace paragraph [0012], with the following amended paragraph:

To achieve these objects of this invention, an integrated circuit chip package is provided. An integrated circuit chip is attached to a substrate; a stress buffering material only covers corners of the integrated circuit chip; and an encapsulation material coats the integrated circuit chip and a portion of the substrate.

In accordance with the objects of this invention, a method for encapsulating an integrated circuit chip is achieved. An integrated circuit chip is attached to a substrate. A dam is formed surrounding the integrated circuit chip. All corners of the integrated circuit chip are covered with a stress buffering material. The integrated circuit chip and all of the substrate within the dam are coated with an encapsulation material wherein the encapsulation material covers the stress buffering material and wherein the stress buffering material prevents delamination of the encapsulation material at the corners of the integrated circuit chip.

Please replace paragraph [0026], with the following amended paragraph:

FIG. 6 shows an oblique view of the die corner. Material 30 covers the corner of the die. The die 12 has a first surface and a second surface. The second surface is attached to the substrate 10. A part of the first surface 11 is covered by the stress buffering material 30, while another part of the first surface 11 is not covered by the stress buffering material 30. FIG. 7 is an enlarged cross-sectional view of the chip 12, showing the active metal circuit layer 33. The stress buffer material layer 30 is shown covering the corner of the die. Encapsulation material 32 covers the entire die.